/ Descriptions

TO-220F

Schottky Barrier Diode in a TO-220F Plastic Package.

/ Features

Low forward voltage drop,low power losses,High efficiency operation.

/ Applications

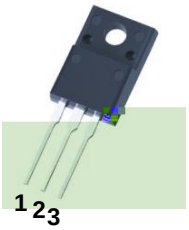
OR-ing DC-DC

For use in high frequency inverters, switching power supplies, freewheeling diodes, OR-ing diode, dc-to-dc converters and reverse battery protection.

/ Equivalent Circuit



/ Pinning



PIN1 Anode PIN 2 Cathode PIN 3 Anode

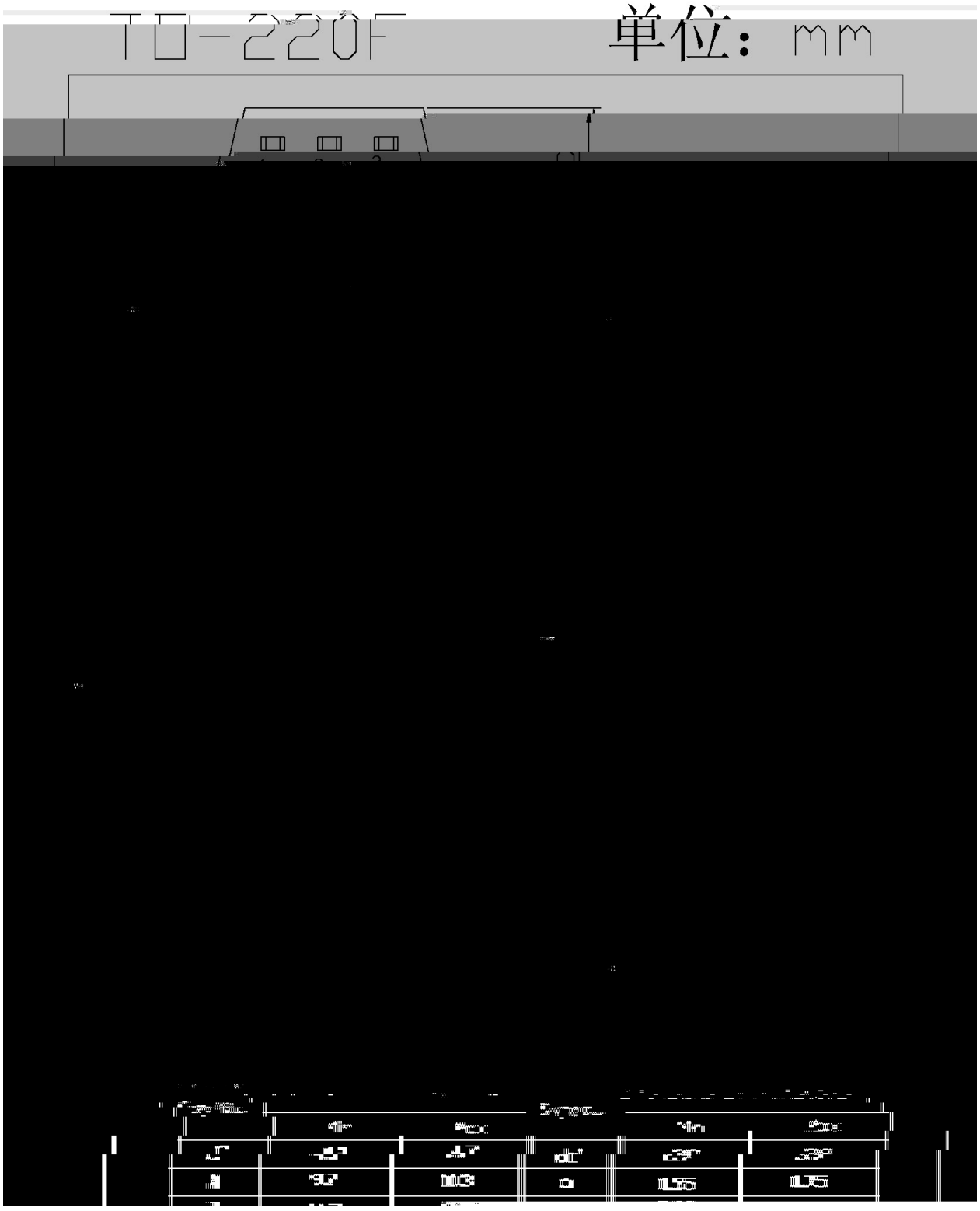
/ h_{FE} Classifications & Marking

See Marking Instructions.

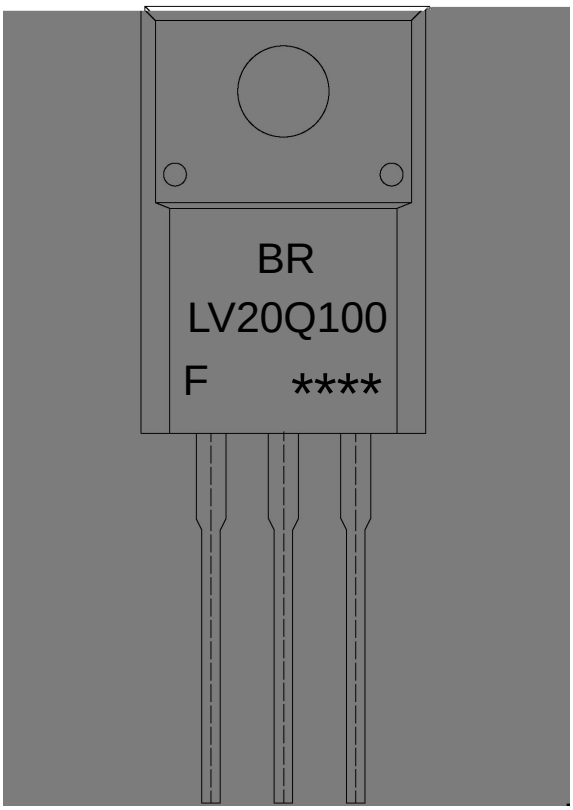
Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage	V_{RM} V_{RSM}	100	V
Average Rectified Forward Current	$I_{F(AV)}$	1×20	A
Non Repetitive Peak Surge Current	I_{FSM}	160	A
Thermal Resistance Junction to Case	$R_{\theta Jc}$	4.6	/W
Junction and Storage Temperature Range	T_j T_{stg}	-40 +150	

Parameter	Symbol	R				
Breakdown Voltage	V_{BR}	I =1mA(Ta=25)	100			V
Forward Voltage	V_F	I_F =5A(Ta=25)		0.516		V
		I_F =10A(Ta=25)			0.60	V
		I_F =5A(Ta=125)		0.455		V
		I_F =10A(Ta=125)			0.58	V
Instantaneous Reverse Current	I_R Note 1	V_R=100V(Ta=25)			150	μA A

/ Package Dimensions



/ Marking Instructions



BR

LV20Q100

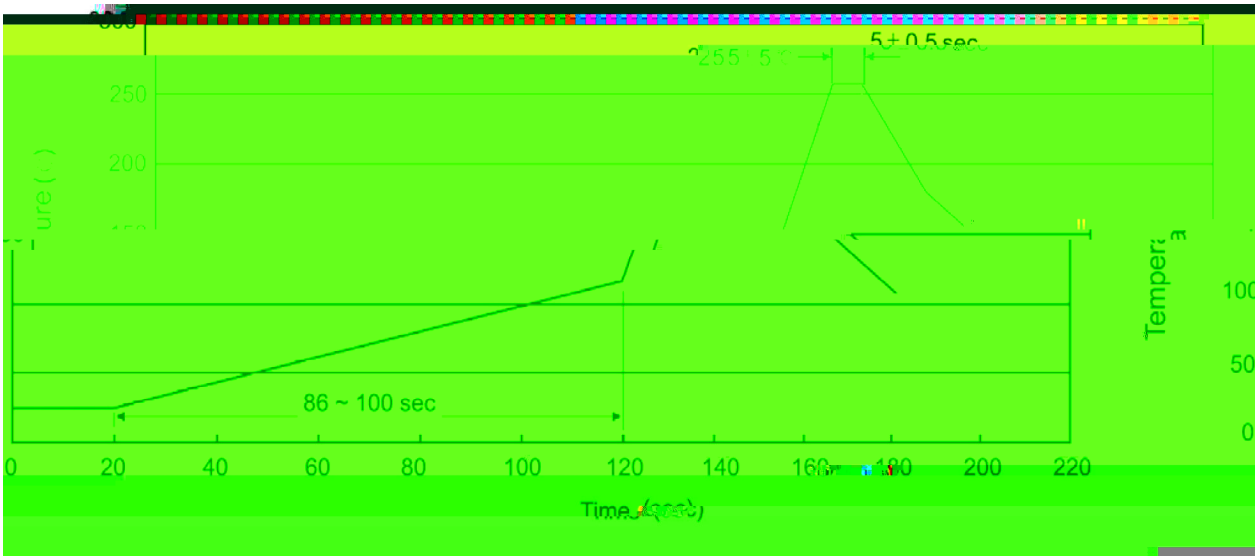
F:

****

Note:

BR:	Company Code
LV20Q100:	Product Type
F:	Package Code
****:	Lot No. Code, code change with Lot No.

( ) / Temperature Profile for Dip Soldering(Pb-Free)



				Note:	
1	25	150	60	90sec;	1.Preheating:25~150 , Time:60~90sec.
2	255±5			5±0.5sec;	2.Peak Temp.:255±5 , Duration:5±0.5sec.
3		2	10	/sec.	3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

270±5	10±1 sec.	Temp.:270±5	Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type	Units			Dimension (unit mm^3)
	Units/Bag /	Bags/Inner Box /	Units/Inner Box /	